

Amendments to the Claims:

The following listing replaces all prior listing of claims in the application.

Listing of Claims

1. (Currently amended) A lithographic method comprising the pressing of a substrate, the method comprising:

~~a preparation step during which~~ preparing a substrate surface is covered with by forming a composite layer on the substrate, wherein forming the composite layer comprises forming an internal sub-layer of curable material and curing the internal sub-layer, and forming an external sub-layer adjacent to the cured internal sub-layer;

~~a pressing step in which a mold comprising a pattern of recesses and protrusions is pressed so as to penetrate a portion of the thickness of the layer, wherein~~ the protrusions of the mold penetrate into the external sub-layer until the protrusions contact the internal sub-layer;

performing at least one etching step process in which the composite layer is etched until ~~parts~~ portions of a surface of the substrate have been exposed; and

~~a substrate etching step, wherein the substrate is etched using an etching pattern defined by the mold pattern~~

~~wherein the preparation step further comprises forming an internal sub-layer or curable material and curing the internal sub-layer, and forming an external sub-layer adjacent to the internal sub-layer, and~~

~~wherein the pressing step further comprises penetrating the protrusions of the mold into the external sub-layer until the protrusions contact the internal sub-layer.~~

2. (Currently amended) The method according to claim 1, wherein forming the internal sub-layer is formed comprises forming the internal sub-layer in contact with the substrate surface and wherein, during the performing at least one etching step;

comprises removing the internal sub-layer is removed in the regions defined by
recesses of formed in the external sub-layer, and, wherein during etching the substrate
comprises etching step, regions of the substrate is etched through exposed by the
recesses.

3. (Currently amended) The method according to claim 1, wherein forming
the internal sub-layer and the external sub-layer comprise forming the same material.

4. (Currently amended) The method according to claim 1, wherein curing
the internal sub-layer comprises a ~~heat treatment of~~ heating the internal sub-layer at a
temperature higher than its a curing temperature of the internal sub-layer, and wherein
~~the pressing step the mold comprises is carried out pressing~~ at a pressing temperature
higher than a glass transition temperature of the external sub-layer.

5. (Currently amended) The method according to claim 1, wherein forming
the internal sub-layer of a curable material comprises forming a polymer.

6. (Currently amended) The method according to claim 1, wherein forming
the internal sub-layer of a curable material comprises forming a resin that is formulated
configured to be cross-linked.

7. (Currently amended) The method according to claim 5, wherein forming
the internal sub-layer of a curable material comprises forming one of a negative resin or
a positive resin.

8. (Currently amended) The method according to claim 1, wherein forming
the internal sub-layer ~~has~~ comprises forming a sub-layer having a thickness of
0.01 micron to 1 micron.

9. (Currently amended) The method according to claim 1, wherein forming
the external sub-layer comprises forming the thickness of the external sub-layer is to a
thickness less than ~~the~~ a depth of the pattern of recesses.

10. (Currently amended) The method according to claim 6, wherein forming the curable material a resin comprises forming one of a negative resin or a positive resin.

11. (New) A lithographic method comprising:

forming a first layer on a substrate, the first layer comprising a curable material, and curing the first layer;

forming a second layer on the first layer, the second layer comprising a deformable material;

pressing a mold against the second layer, wherein protrusions of the mold form recesses in the second layer that expose portions of the first layer;

etching the exposed portions of the first layer using the second layer as an etch mask, and exposing surface regions of the substrate; and

etching the surface regions of the substrate.